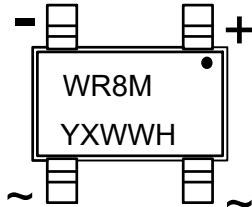


## Ultrasoft Recovery Bridge



Note:

- 1.The silk screen is WR8M ;
- 2.YXWWH means to produce LOT.

### Features

- Low profile space
- Ideal for printed circuit board
- Low reverse leakage
- Ultrafast reverse recovery time
- Applied in power supply equipment
- High ring wave immunity capability

### Benefits

- Case: NBS
- Terminals: Solderable Per MIL-STD-750
- Approx. Weight: 82mg 0.0029oz

### Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	WR8M	Units
Maximum Repetitive Peak Reverse Voltage	VRRM	1000	V
Maximum RMS voltage	VRMS	700	V
Maximum DC Blocking Voltage	VDC	1000	V
Average Rectified Output Current	I <sub>o</sub>	0.8	A
Reverse Recovery Time. IF=0.5A,IR=1A,IRR=0.25A	T <sub>rr</sub>	10	us
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	IFSM	25	A
I <sup>2</sup> t rating for fusing ( 1ms< t < 10ms)	I <sup>2</sup> t	2.6	A <sup>2</sup> S
Maximum Forward Voltage at 0.4 A	V <sub>F</sub>	1.1	V
Maximum DC Reverse Current @TA=25 °C at Rated DC Blocking Voltage @TA=125 °C	I <sub>R</sub>	5 100	μA
Typical Junction Capacitance (Note1)	C <sub>j</sub>	82	pF
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150	°C
Typical thermal resistance (Note 2)	R <sub>thJL</sub> R <sub>thJA</sub>	35 180	°C/W

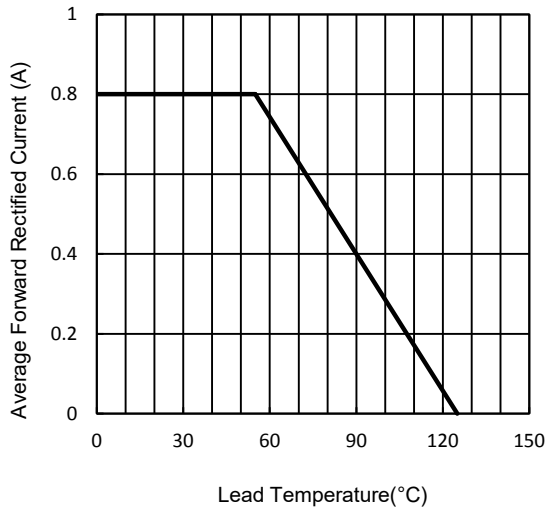
Note: 1. Measured at 1MHz and applied reverse voltage of 4 VDC.

2. Thermal resistance junction to case, lead and ambient in accordance with JESD-51.

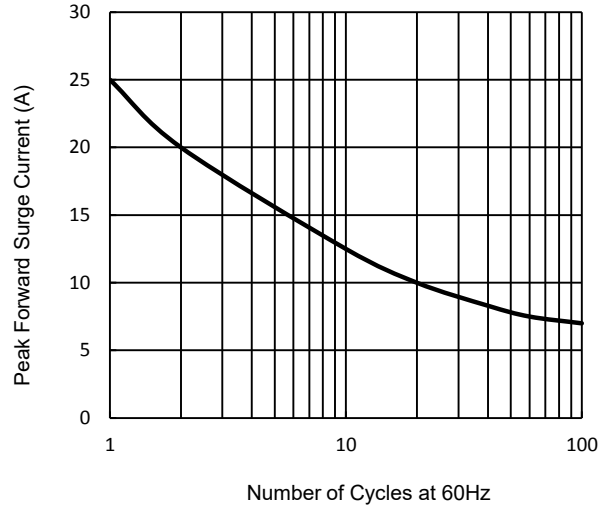
Unit mounted on glass-epoxy substrate with 1oz/ft<sup>2</sup> 20x20 mm copper pad per pin with heatsink

**RATINGS AND CHARACTERISTICS CURVES** (TA = 25 °C unless otherwise noted)

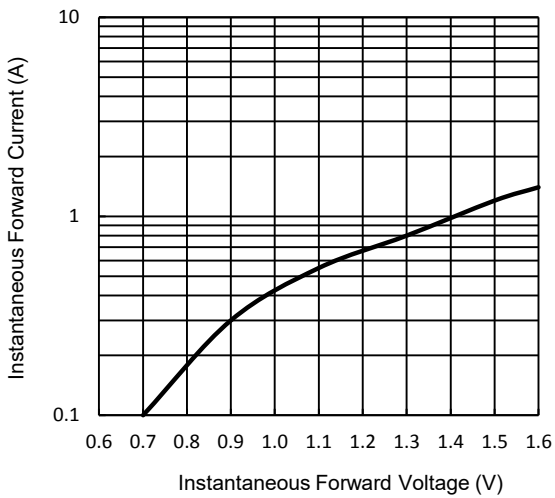
**Fig.1 Foward Current Derating Curve**



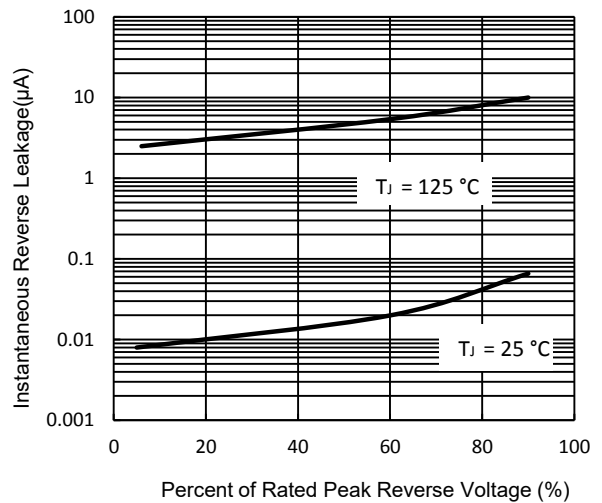
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**



**Fig.3 Typical Forward Current Characteristics**



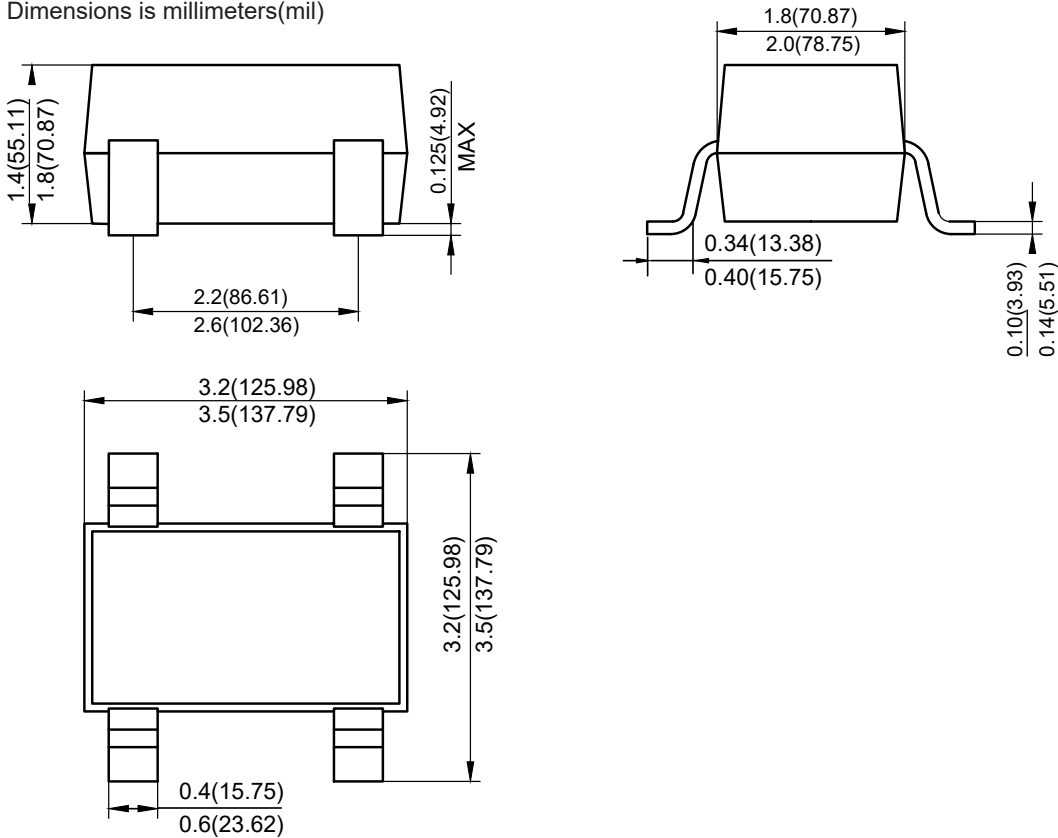
**Fig.4 Typical Reverse Characteristics**



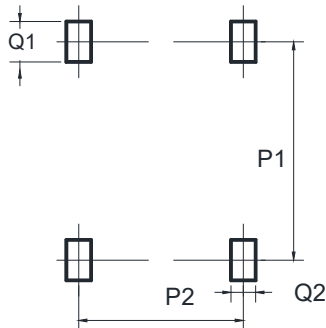
**PACKAGE OUTLINE DIMENSIONS**

**NBS**

Dimensions is millimeters(mil)



**NBS Suggested Pad Layout**



Dimensions is millimeters

UNIT		P1	P2	Q1	Q2
mm	min	3.1	2.4	0.8	0.8
mil	min	122.05	94.5	31.50	31.50